



Product / Process Change Notice

No.: Z200-PCN-DM202203-02-A

Date: March 11, 2022

Change Title : 128Mb x16 SDR (TFBGA-54 package) technology migration from 65nm to 46nm.

Change Classification: Major Minor with customer notification Minor without customer notification
Change item : DataSheet Design Raw Material Wafer FAB Assembly Testing Packing Others

Affected Product(s) :

W9812G6JB75I , W9812G6JB-75 , W9812G6JB-6I , W9812G6JB-6 , W9812G6JB-5.

Description of Change(s)

Technology migration (65nm to 46nm) for 128Mb SDR.

Reason for Change(s) :

According to Winbond product roadmap, launch new 128Mb SDR with 46nm technology.

Impact of Change(s) : (positive & negative)

Form : No Change

Fit : No Change (Please refer to attachment I)

Function : No Concern (Compatible between 65nm and 46nm, refer to attachment II)

Reliability : No Concern (Please refer to attachment III)

Hazardous Substances: No Concern (Please refer to attachment IV)

Qualification Plan/ Results :

Base on Winbond EV data result and AG1 reliability report, the new product meets our criteria and no quality concern.

Implementation Plan :

The follow-up disposition of 65nm 128Mb x16 SDR:

- 1) The date of last-buy orders for the 65nm 128Mb x16 SDR: September 13, 2022.
- 2) The last shipment date of the 65nm 128Mb x16 SDR: December 13, 2022.

Date Code: onward Lot No: onward Proposed first ship date: June 13, 2022

Originator:
(QA)

Hyhuang

**Approval: (QA
Dept. Manager)**

Michael

Approval:
(QRA Director)

Chang Shu Cheng

**Contact for Questions
& Concerns**

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